

Title (en)

AFTER-TREATMENT PROCESS FOR INCREASING THE HOT STRENGTH OF A SHAPED PART PRODUCED FROM PARTICULATE MATERIAL AND BINDER, 3D PRINTING ARRANGEMENT AND SHAPED PART

Title (de)

NACHBEHANDLUNGSVERFAHREN ZUR ERHÖHUNG DER HEIßFESTIGKEIT EINES AUS PARTIKELMATERIAL UND BINDEMittel GEFERTIGTEN FORMTEILS, 3D-DRUCK-ANORDNUNG UND FORMTEIL

Title (fr)

PROCÉDÉ DE RETRAITEMENT DESTINÉ À L'AUGMENTATION DE LA RÉSISTANCE À CHAUD D'UNE PIÈCE MOULÉE RÉALISÉE AVEC UN MATÉRIAU PULVÉRULENT ET UN LIANT, UN ENSEMBLE D'IMPRESSION 3D ET UNE PIÈCE MOULÉE

Publication

**EP 3638435 A1 20200422 (DE)**

Application

**EP 18716522 A 20180319**

Priority

- DE 102017111266 A 20170523
- EP 2018056895 W 20180319

Abstract (en)

[origin: WO2018215113A1] The invention provides an after-treatment process for increasing the hot strength of a shaped part (100) produced from particulate material and binder in which the shaped part (100) is a shaped part produced by 3D printing (S72) and, after its production, is heated by using a heating device (40) (S30) and the heated shaped part (100) is exposed to an atmosphere created by feeding in water and enriched with gaseous water (S50).

IPC 8 full level

**B22C 1/16** (2006.01); **B22C 1/18** (2006.01); **B22C 9/12** (2006.01)

CPC (source: EP US)

**B22C 1/162** (2013.01 - EP US); **B22C 1/18** (2013.01 - US); **B22C 1/188** (2013.01 - EP); **B22C 9/123** (2013.01 - EP US); **B28B 1/001** (2013.01 - US); **B28B 11/241** (2013.01 - US); **B33Y 10/00** (2014.12 - EP US); **B33Y 30/00** (2014.12 - EP); **B33Y 70/00** (2014.12 - US); **C04B 28/26** (2013.01 - EP); **B33Y 80/00** (2014.12 - US); **C04B 2111/00181** (2013.01 - EP); **C04B 2111/00905** (2013.01 - EP)

Citation (search report)

See references of WO 2018215113A1

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

Designated extension state (EPC)

BA ME

DOCDB simple family (publication)

**WO 2018215113 A1 20181129**; EP 3638435 A1 20200422; JP 2020520808 A 20200716; US 2020086381 A1 20200319

DOCDB simple family (application)

**EP 2018056895 W 20180319**; EP 18716522 A 20180319; JP 2019564133 A 20180319; US 201816615580 A 20180319